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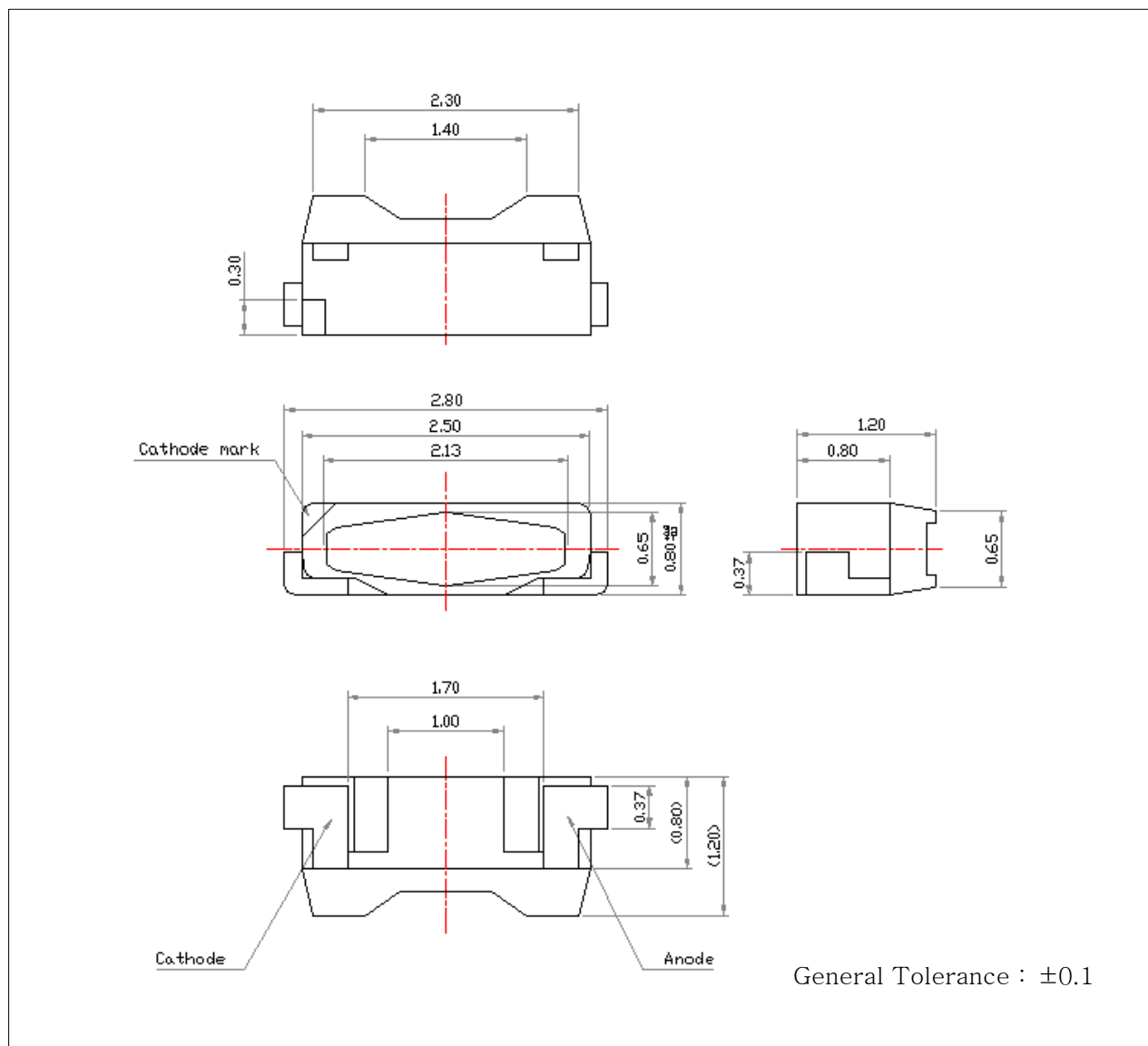
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1. Features

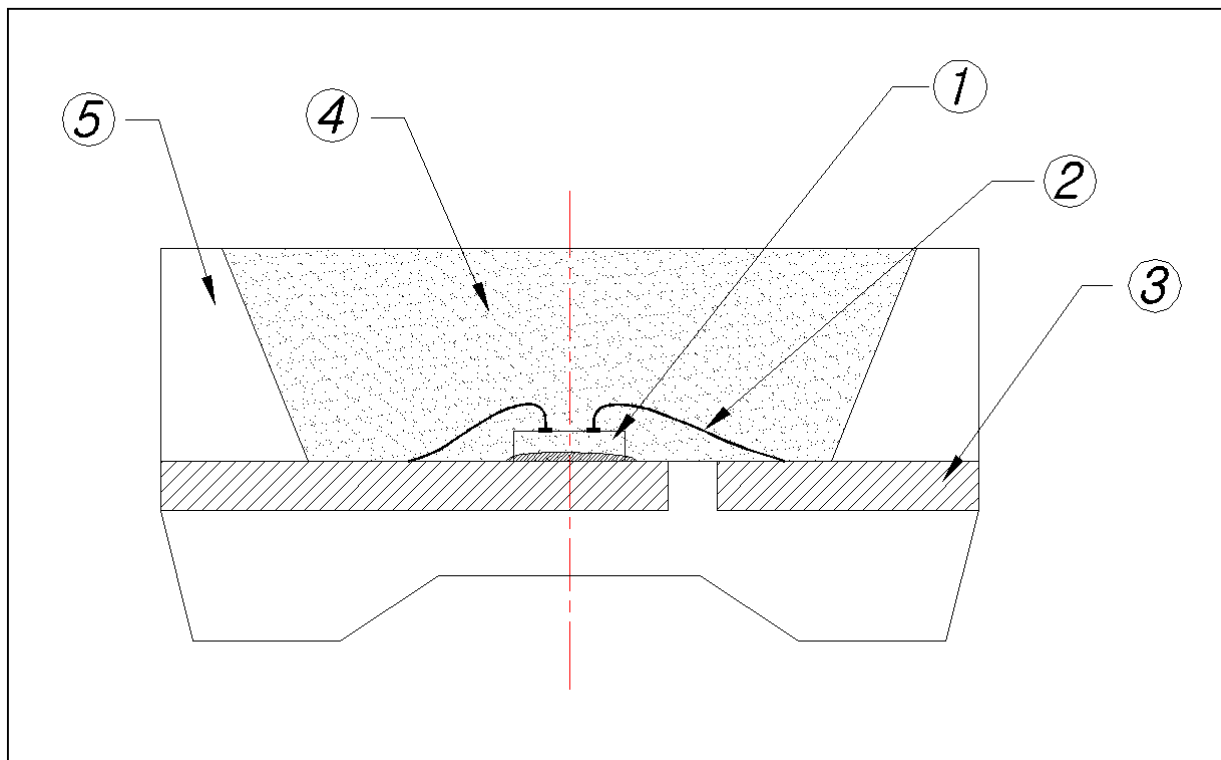
- Package : SMD Side View Type
- Yellow colored diffusion
- $2.8 \times 1.2 \times 0.8$ mm(L×W×H) small size surface mount type
- Color Coordinates : $x = 0.31$, $y = 0.32$ acc. to CIE 1931, at $I_f = 20$ mA
- Viewing angle : extremely wide(110°)
- Technology : InGaN
- ESD Class(Mil Std-883d Methode 3015.7) based on Human Body Model(HBM) : 950V
- Soldering methods : IR reflow soldering
- Taping : 8 mm conductive black carrier tape & antistatic clear cover tape.
3,500pcs/reel, $\Phi 180$ mm wheel

2. Outline dimensions

(unit : mm)



3. Package material



(1) Material construction

Number	Item	Material
1	LED Chip	InGaN/Sapphire
2	Au wire	1.0mil Gold Wire
3	Lead Frame	Copper Alloy/Ni/Ag plating
4	Encapsulation	Encapsulate + YAG phosphor
5	Heat-Resistant Polymer	PPA

4. Absolute Maximum Ratings

(TA = 25℃)

Parameter	Symbol	Value	Unit
Power dissipation	P_D	120	mW
Forward Current	I_F	30	mA
* ¹ Peak Forward Current	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-30 ~ +85	℃
Storage Temperature	T_{stg}	-40 ~ +100	℃
Soldering Temperature	T_{sol}	260℃ for 10 seconds	

*1.Duty ratio = 1/16, Pulse width = 0.1ms

5. Electrical – Optical Characteristics

(TA = 25℃)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
ESD Check Forward Voltage	V_{F2}	$I_F = 10\mu A$	2.0	–	–	V
Reverse Current	I_R	$V_R = 5V$	–	–	10	μA
* ⁶ Half Angle	$\theta_{1/2}$	$I_F = 20mA$	–	± 55	–	deg

*6. $\theta_{1/2}$ is the off-axis angle where the luminous intensity is 1/2 the peak intensity

6. Ranks

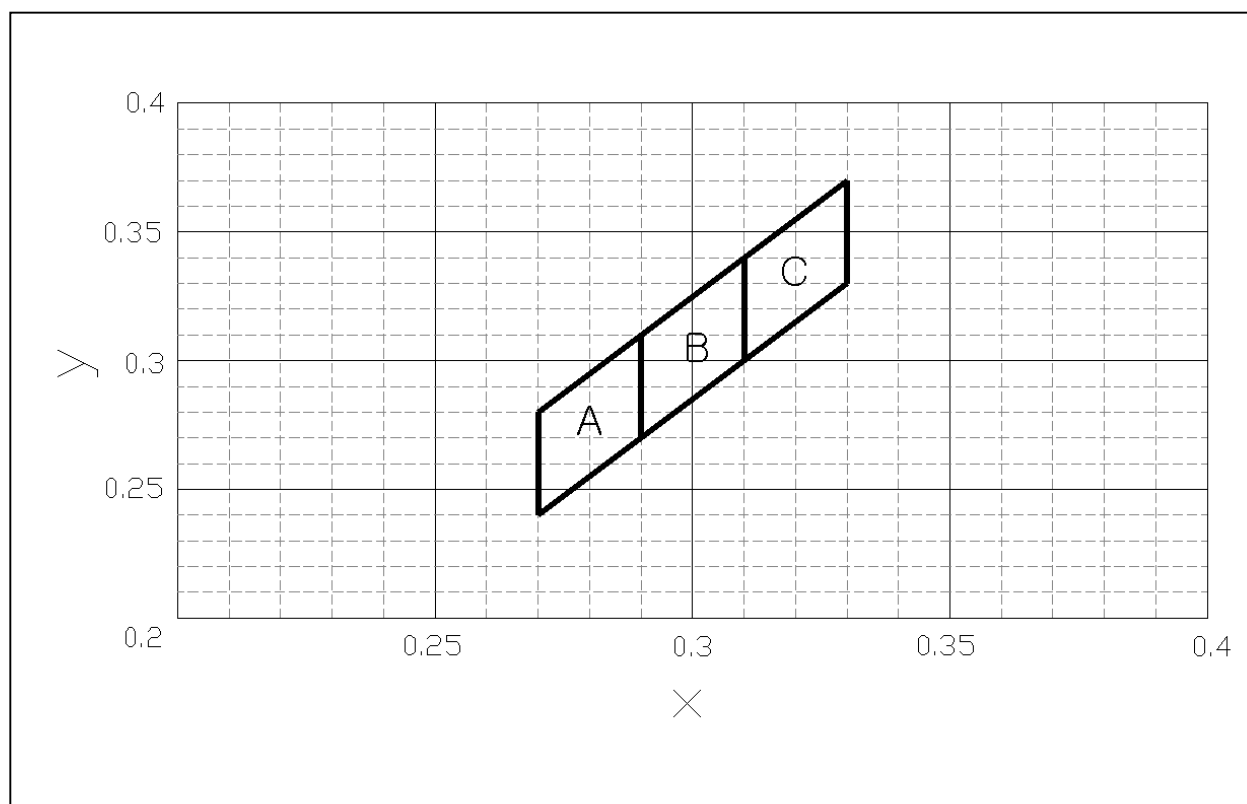
(1) Chromaticity Coordinates ranks

(If=20mA, Ta=25℃)

	Rank A			
x	0.27	0.27	0.29	0.29
y	0.24	0.28	0.27	0.31

	Rank B			
x	0.29	0.29	0.31	0.31
y	0.27	0.31	0.30	0.34

	Rank C			
x	0.31	0.31	0.33	0.33
y	0.30	0.34	0.33	0.37



- * The CIE(1931) standard colorimetric system
- * Chromaticity coordinates Measured : 0.01sr(CIE. LED_B)
- * Measurement Uncertainty of the Color Coordinates : ± 0.01

(2) Luminous intensity ranks

(Ta=25℃)

Iv RANK	Test Condition	Min.	Typ.	Max.	Unit
R	I _F = 15mA	291		405	mcd
S		405		583	
T		583		810	
R	I _F = 20mA	360		500	
S		500		720	
T		720		1000	

* Luminous intensity is tested at a current pulse duration of 25 ms and an accuracy of ±11%.

* Luminous Intensity Measured : 0.01sr(CIE. LED_B)

(3) Forward Voltage

(Ta=25℃)

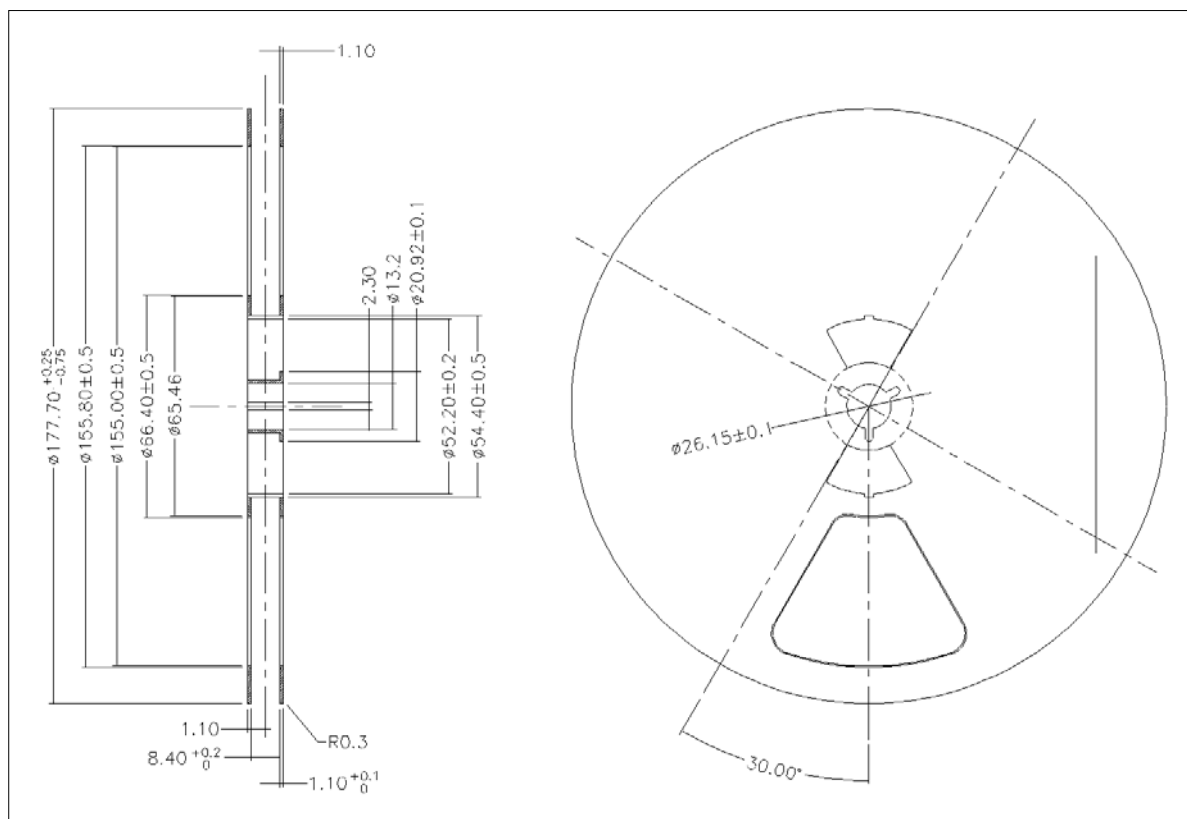
Test Condition	Min.	Typ.	Max.	Unit
I _F = 15mA		3.26	3.45	V
I _F = 20mA		3.4	3.6	

* Voltages are tested at a current pulse duration of 1 ms and an accuracy of ±0.1V.

7. Taping

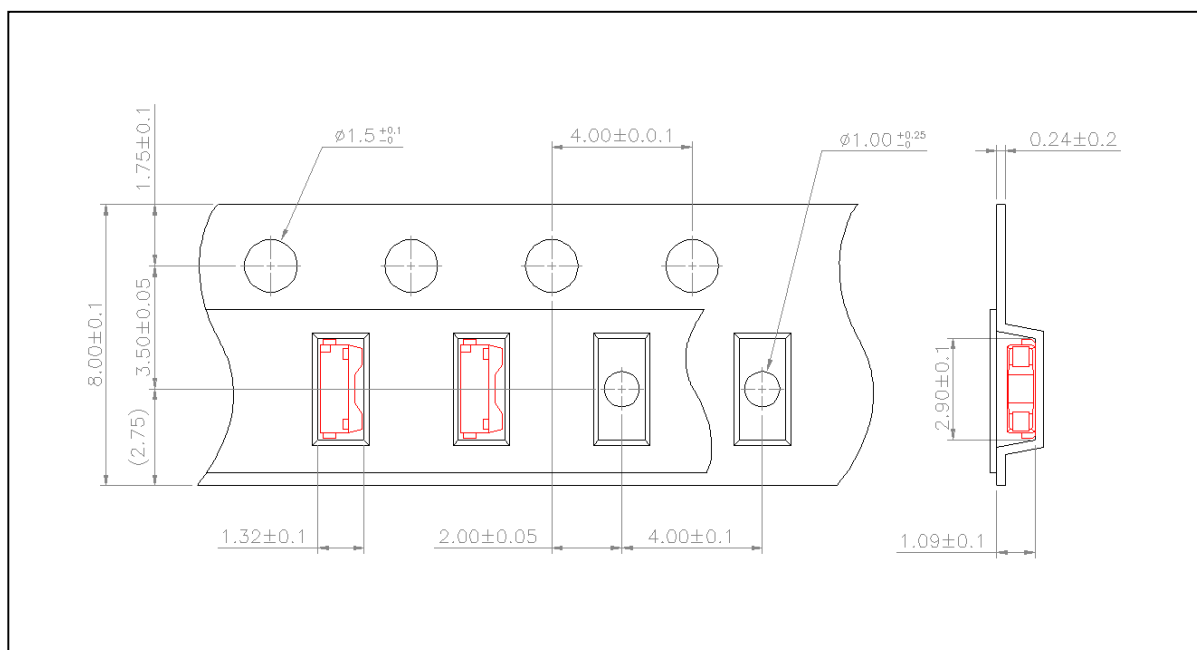
(1) Dimension of wheel((Material : PS Conductive, 10E9~12Ω)

(Unit : mm)

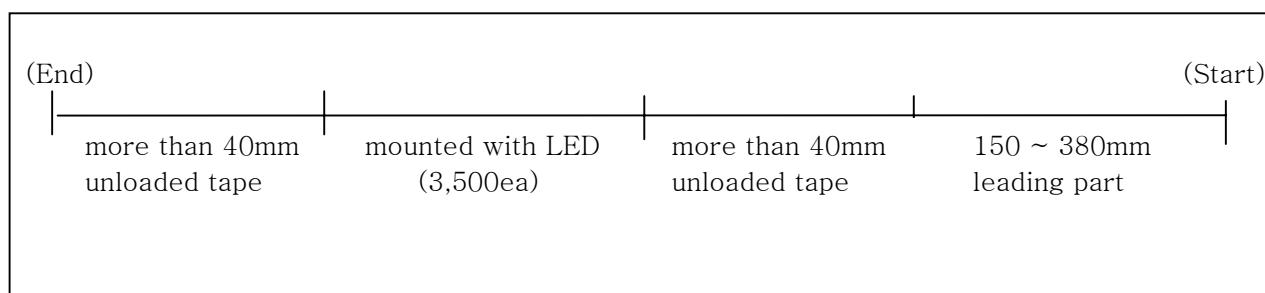


(2) Dimension of tape(Material : PS Conductive, 10E4~5Ω)

(Unit : mm)

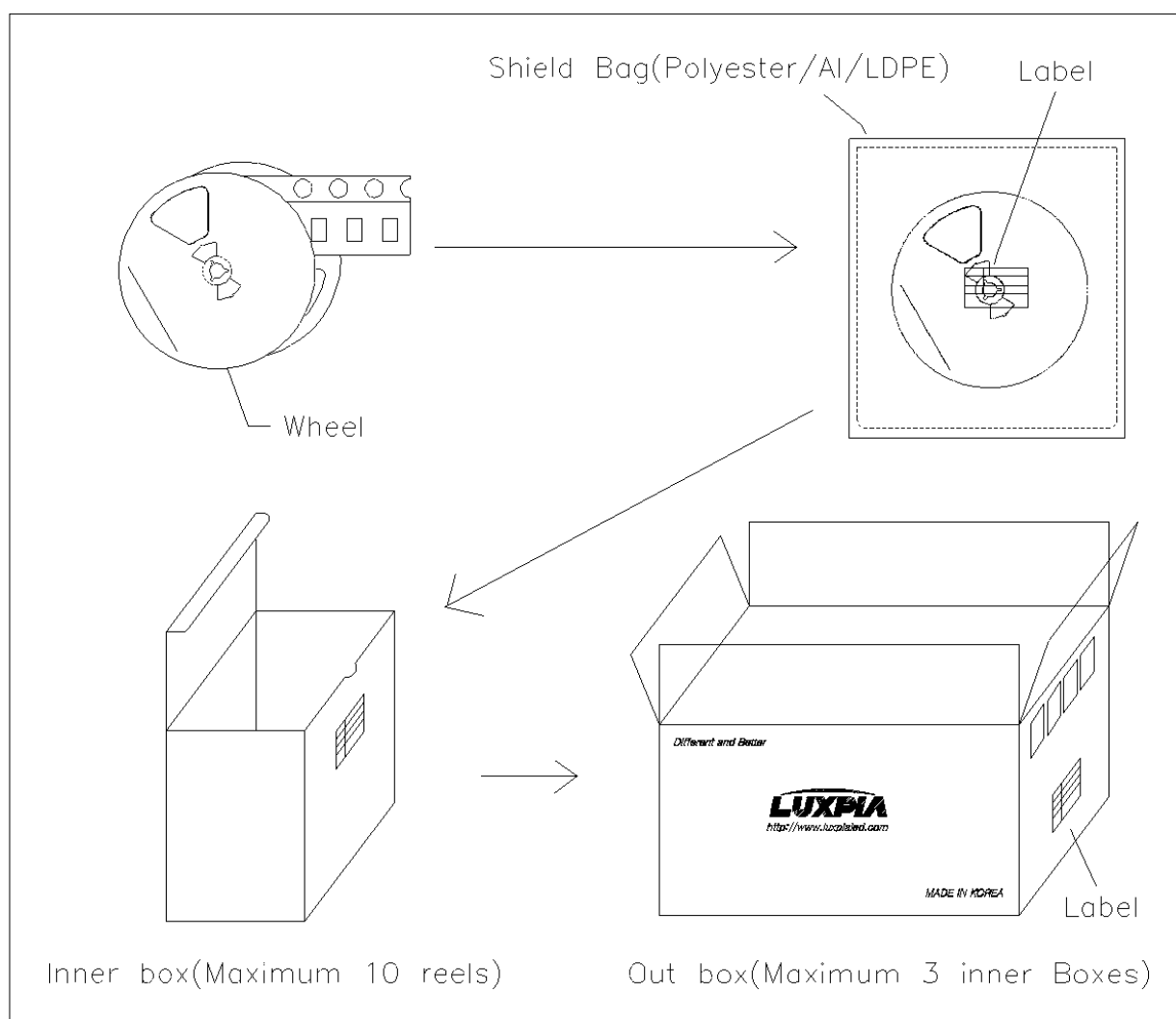


(3) Details of CHIPLEDs loading on tape



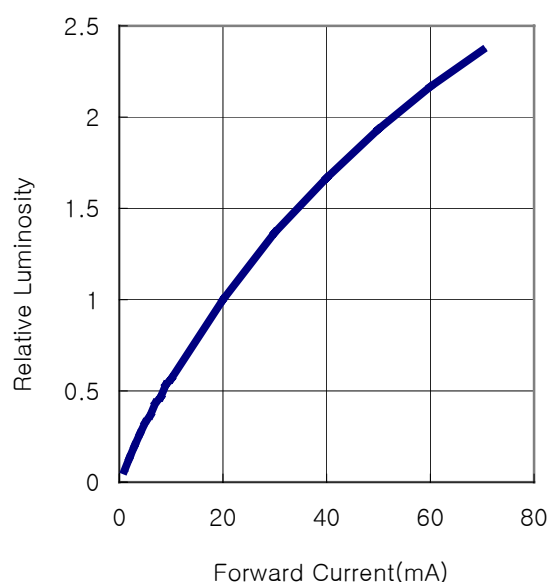
(4) Loading quantity per reel : 3,500pcs

8. Packing Struction

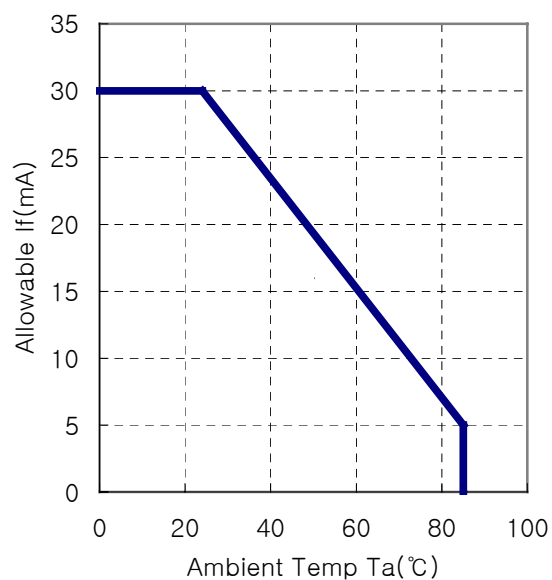


9. Characteristic Diagrams

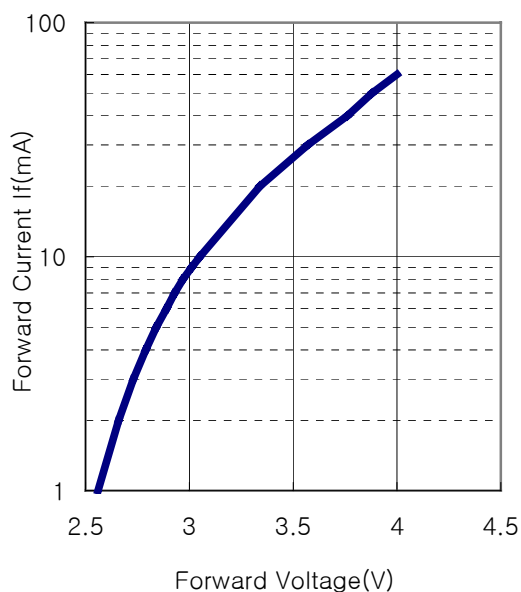
(1) Relative Luminous Intensity
vs Forward Current (I_F - I_v)



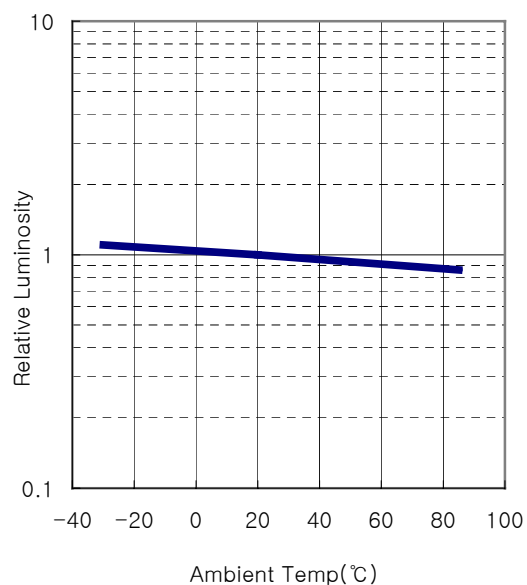
(2) Max. Permissible Forward Current



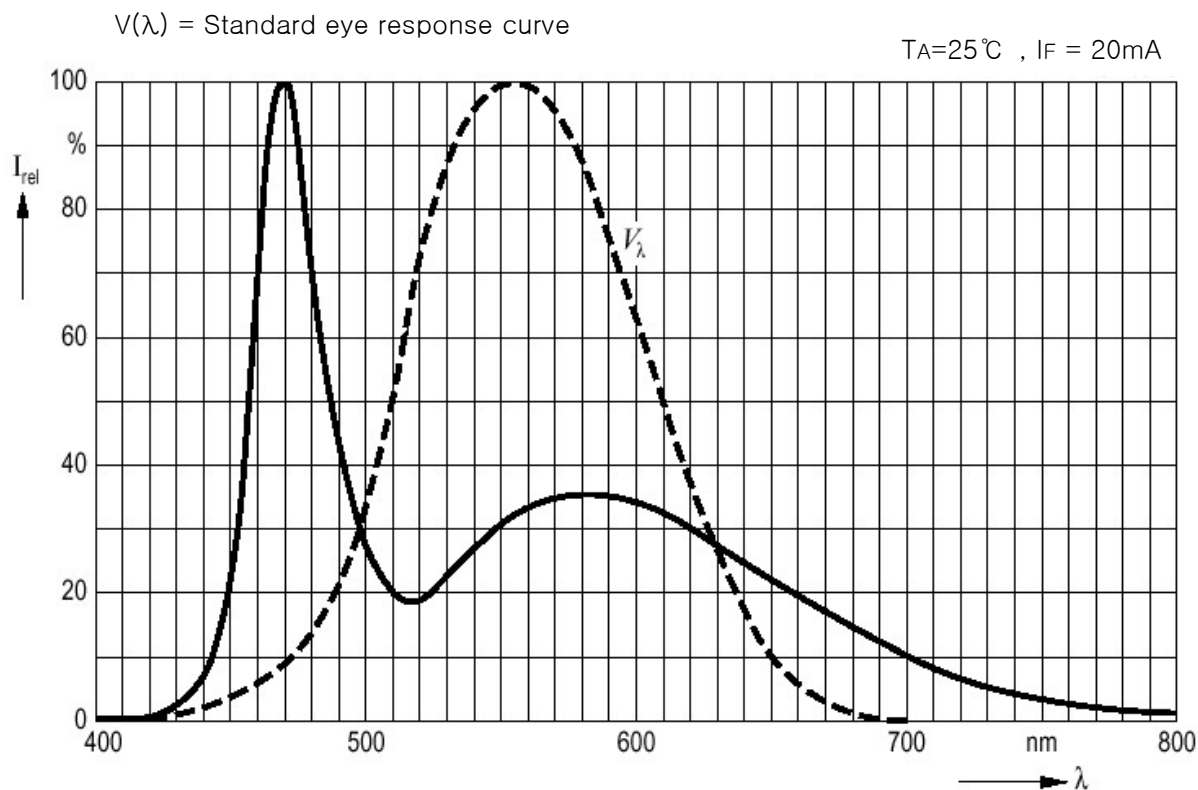
(3) Forward Current vs Forward Voltage (I_F - V_f)



(4) Ambient Temperature vs Relative Luminosity

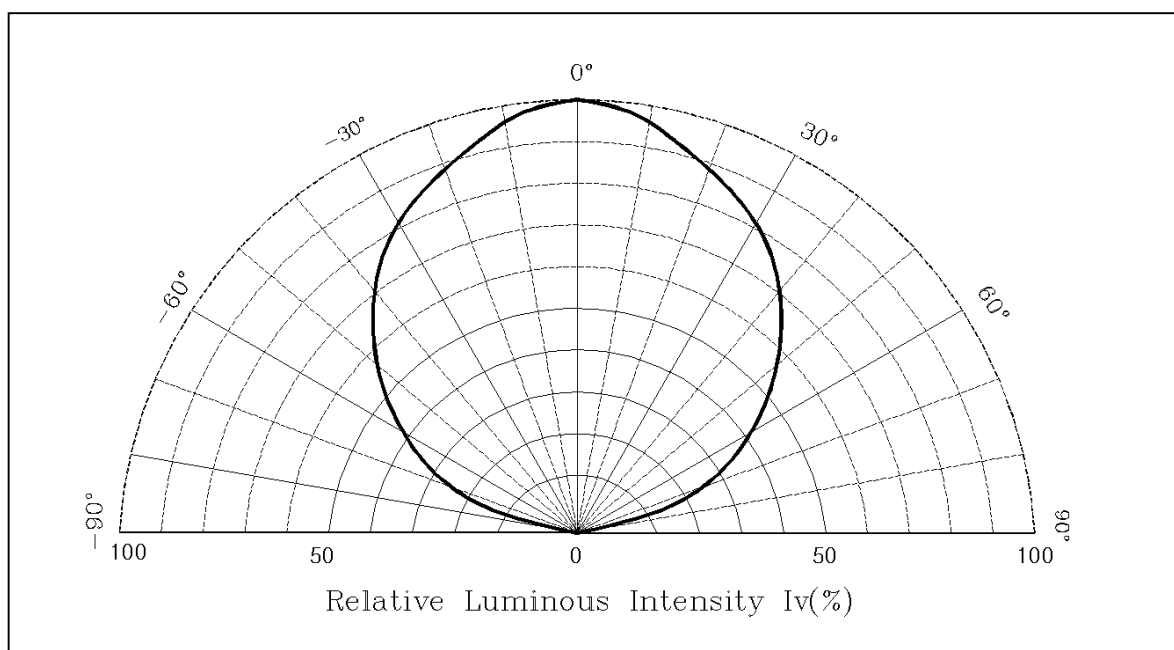


(4) Relative Spectral Emission



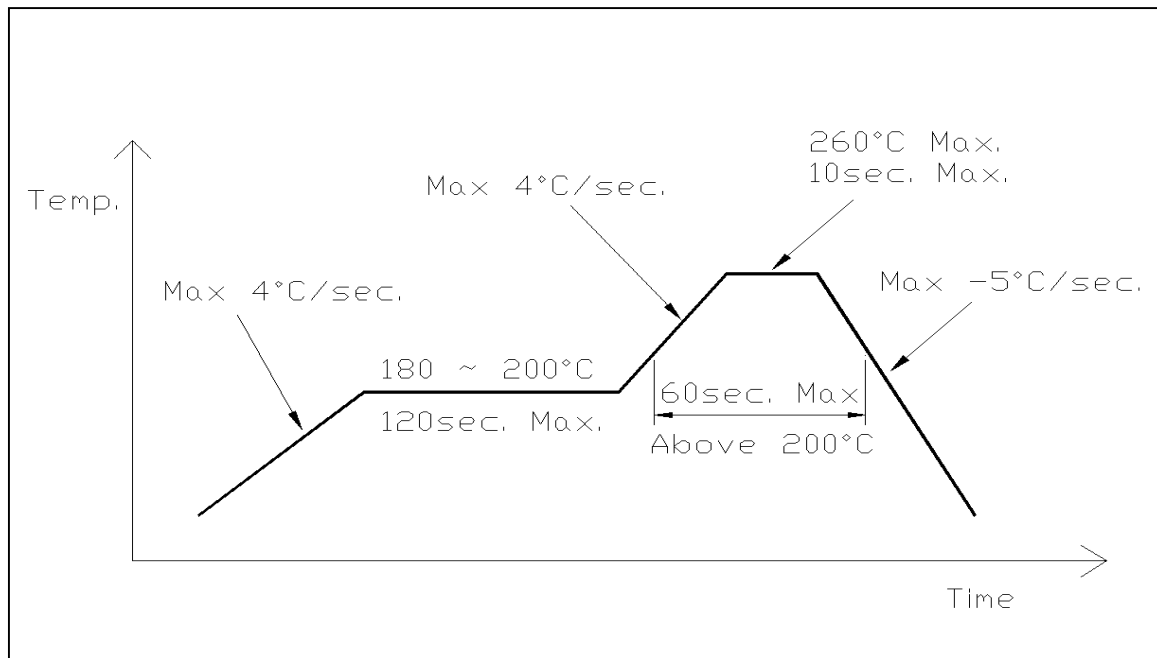
(5) Radiation Characteristic

$T_A=25^\circ\text{C}$, $I_F = 20\text{mA}$



10. Precautions to taken

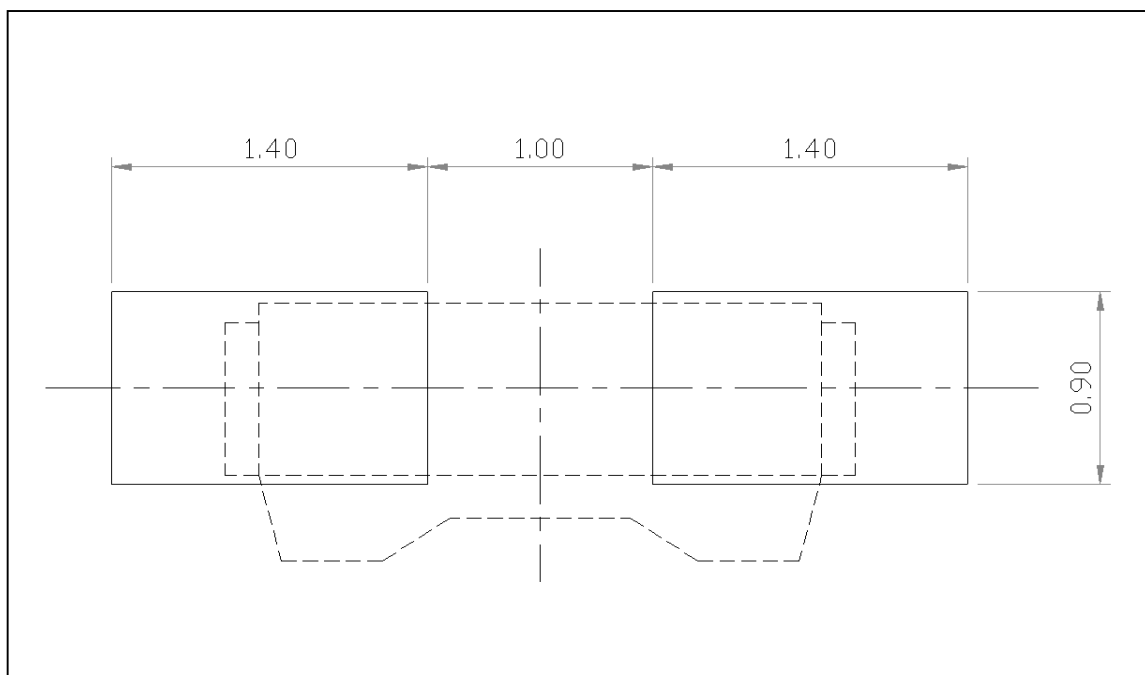
(1) Reflow soldering



(2) For manual solder

Not more than 3sec @max 350°C , under soldering iron

(3) Recommendable soldering pattern(For reflow soldering)



11. Reliability

(1) The Reliability criteria of SMD LED

ITEM	Symbol	Test Condition	Limit	
			Min.	Max.
Forward Voltage	V _F	I _F = 20mA	I.V × 0.8	I.V × 1.2
Reverse Voltage	V _R	I _R = 10μA	LSL	—
Luminous intensity	I _v	I _F = 20mA	I.V × 0.7	I.V × 1.3

* I : Initial Value U : Upper Spec Limit L : Lower Spec Limit

(2) Results of reliability Test

NO	Item	Test Conditions	Test Hours /Cycle	Sample Size	Ac/Re
1	Temperature Cycle	H : +100℃ 30min 25℃ 5min L : -40℃ 30min	100 Cycle	21 pcs	0/1
2	High Temperature Operating Life	TEMP : 85℃ (I _F =5mA)	1000HR's	21 pcs	0/1
3	Low Temperature Operating Life	TEMP : -30℃ (I _F =20mA)	1000HR's	21 pcs	0/1
4	DC Operating Life	TEMP : 24℃ (I _F =30mA)	500HR's	21 pcs	0/1
5	High Humidity Heat Operating Life	60℃/90% RH, (I _F =15mA)	500HR's	21 pcs	0/1
6	Solder Heat Test	260℃, 10sec.	2 Time	21 pcs	0/1

12. Precautions in use

(1) Soldering Conditions

- 1) When soldering, leave minimum clearance between the resin and the soldering point.
- 2) Maximum allowable soldering conditions
Soldering dipping : 260 degrees C max., 10 seconds max., 2 time.
Soldering iron : 350 degrees C max., 3 seconds max., 1 time, power 40w max.
- 3) Contact between molten solder and the resin must be avoided.
- 4) Correction the soldered position after soldering must be avoided.
- 5) In soldering, do not apply any stress to the lead frame, particularly when heated.
- 6) When other SMD parts on the same circuit board and adhesive is to be cured, maximum allowable conditions are : 120 degrees C max., 60 seconds max.

(2) Lead forming and cut

- 1) Lead forming must be done below the tie bar cutting portion.
- 2) When forming a lead, do not stress the resin case.
- 3) Lead forming must be done before soldering.
- 4) Cutting the lead frame at high temperature may result in personal injury.
Cut the lead frame at room temperature.

(3) Assembly

- 1) Do not apply any stress to the lead frame while assembling.
- 2) When mounting products onto PCBs, the pitch between the mounting holes must match the pitch of the LEDs.

(4) Static Electricity

- 1) These products are sensitive, a high standard of care must be used. Particularly if an over-current and over-voltage which exceeds the Absolute Maximum Rating of Products is applied, the overflow in energy may cause damage to, or possibly result in destruction of, the Products. Customer shall take absolutely secure countermeasures against static electricity and surge when handling Products.
- 2) A protection device should be installed in the LED driving circuit, which dose not exceed the max. rating for surge current during on/off switching.
- 3) Proper grounding of Products, use of conductive mat, semiconductive working uniform and shoes, and semiconductive containers are considered to be effective as countermeasures against static electricity and surge.
- 4) A soldering iron with a grounded tip is recommended. An ionizer should also be installed where risk of static generation is high.

(5) Safety Precautions

- 1) Users must comply with the laws and public regulations concerning safety.
The light output of the products may cause injuries to human eyes in circumstances where the products are viewed directly with unshielded eyes for more than a few seconds.

Different and Better

13. Revision history sheet

Spec NO.			
Title	Specification for Approval		
Times	Date	Summary of revision	Remarks
1	2002. 12. 23	신규제정	
2	2003. 01. 10	lv Rank 변경	
3	2003. 03. 04	색좌표 변경 및 IF=15mA 측정조건 추가	